

WEST Search History

[Hide Items](#)[Restore](#)[Clear](#)[Cancel](#)

DATE: Monday, July 09, 2007

<u>Hide?</u>	<u>Set Name</u>	<u>Query</u>	<u>Hit Count</u>
	<i>DB=DWPI; PLUR=YES; OP=ADJ</i>		
<input type="checkbox"/>	L10	JP 2004055839	1
<input type="checkbox"/>	L9	JP 2004055927	1
	<i>DB=JPAB; PLUR=YES; OP=ADJ</i>		
<input type="checkbox"/>	L8	jp2002213078	1
<input type="checkbox"/>	L7	jp20020213078	0
	<i>DB=DWPI; PLUR=YES; OP=ADJ</i>		
<input type="checkbox"/>	L6	jp20020213078	0
<input type="checkbox"/>	L5	jp2002213078	1
<input type="checkbox"/>	L4	jp2002211524	0
	<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>		
<input type="checkbox"/>	L3	jp20020211524	0
<input type="checkbox"/>	L2	jp2002211524	1
<input type="checkbox"/>	L1	6932884	6

END OF SEARCH HISTORY

[First Hit](#) [Previous Doc](#) [Next Doc](#) [Go to Doc#](#)

End of Result Set

☐ [Generate Collection](#) [Print](#)

L1: Entry 6 of 6

File: DWPI

Mar 6, 2003

DERWENT-ACC-NO: 2003-402341

DERWENT-WEEK: 200574

COPYRIGHT 2007 DERWENT INFORMATION LTD

TITLE: Substrate processing apparatus for semiconductor device manufacture, etches and cleans peripheral portion of substrate by etching unit, while substrate is being rotated by chuck assembly

INVENTOR: ITO, K ; MAKITA, Y ; SAITO, T ; SHIRAKASHI, M ; SUZUKI, T ; YAMADA, K

PATENT-ASSIGNEE:

ASSIGNEE	CODE
EBARA CORP	EBAR
ITO K	ITOKI
MAKITA Y	MAKII
SAITO T	SAITI
SHIRAKASHI M	SHIRI
SUZUKI T	SUZUI
YAMADA K	YAMAI

PRIORITY-DATA: 2001JP-0268487 (September 5, 2001)

[Search Selected](#)[Search ALL](#)[Clear](#)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> US 20030041968 A1	March 6, 2003		016	C25F001/00
<input type="checkbox"/> JP 2003077879 A	March 14, 2003		011	H01L021/304
<input type="checkbox"/> WO 2003023825 A2	March 20, 2003	E	000	H01L021/00
<input type="checkbox"/> TW 559953 A	November 1, 2003		000	H01L021/3213
<input type="checkbox"/> EP 1423867 A2	June 2, 2004	E	000	H01L021/00
<input type="checkbox"/> KR 2004028955 A	April 3, 2004		000	H01L021/302
<input type="checkbox"/> CN 1547759 A	November 17, 2004		000	H01L021/00
<input type="checkbox"/> US 6932884 B2	August 23, 2005		000	C23F001/00

DESIGNATED-STATES: CN KR AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LU MC NL
PT SE SK TR AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LT LU LV MC MK NL
PT RO SE SI SK TR

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
US20030041968A1	September 4, 2002	2002US-0233467	
JP2003077879A	September 5, 2001	2001JP-0268487	
WO2003023825A2	September 3, 2002	2002WO-JP08924	
TW 559953A	September 4, 2002	2002TW-0120134	
EP 1423867A2	September 3, 2002	2002EP-0762980	
EP 1423867A2	September 3, 2002	2002WO-JP08924	
EP 1423867A2		WO2003023825	Based on
KR2004028955A	January 29, 2004	2004KR-0701307	
CN 1547759A	September 3, 2002	2002CN-0816766	
US 6932884B2	September 4, 2002	2002US-0233467	

INT-CL (IPC): A47L 15/00; A47L 25/00; C23F 1/00; C25D 17/00; C25F 1/00; H01L 21/00; H01L 21/302; H01L 21/304; H01L 21/306; H01L 21/3213

RELATED-ACC-NO: 2005-724972

ABSTRACTED-PUB-NO: US20030041968A

BASIC-ABSTRACT:

NOVELTY - A chuck assembly holds and rotates a substrate (W). A gas introduction pipe (9) introduces gas into a closable chamber (14) that houses the chuck assembly. An etching unit etches and cleans the peripheral portion of a substrate (W), while the substrate is being rotated by the chuck assembly. A supply passage supplies processing liquid to the etching unit.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for substrate processing.

USE - Used for semiconductor device manufacture.

ADVANTAGE - The peripheral portion of the substrate is etched and cleaned efficiently, while protecting the substrate by supplying relatively small amount of gas.

DESCRIPTION OF DRAWING(S) - The figure shows a cross-sectional view of a substrate cleaning device.

Gas introduction pipe 9

Chamber 14

Substrate W

CHOSEN-DRAWING: Dwg.1/7

TITLE-TERMS: SUBSTRATE PROCESS APPARATUS SEMICONDUCTOR DEVICE MANUFACTURE ETCH CLEAN PERIPHERAL PORTION SUBSTRATE ETCH UNIT SUBSTRATE ROTATING CHUCK ASSEMBLE

DERWENT-CLASS: L03 M11 P28 U11

CPI-CODES: L04-C07; L04-D; M11-H02; M11-H05;

EPI-CODES: U11-C06A1B; U11-C07A; U11-F02A2;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C2003-106951

Non-CPI Secondary Accession Numbers: N2003-320945

[Previous Doc](#)

[Next Doc](#)

[Go to Doc#](#)